



Material Content Data Sheet



Sales Product Name	ITD50N04S4L-04			Issued		29. August 2013		
MA#	MA001116616							
Package	PG-TO252-5-11			Weight*		357.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	1.24	1.24	12378	12378
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		572	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		172	
	non noble metal	copper	7440-50-8	204.243	57.11	57.19	571299	572043
wire	non noble metal	aluminium	7429-90-5	4.207	1.18	1.18	11767	11767
encapsulation	organic material	carbon black	1333-86-4	1.358	0.38		3798	
	plastics	epoxy resin	-	23.763	6.65		66469	
	inorganic material	silicondioxide	60676-86-0	110.669	30.96	37.99	309557	379824
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14189	14189
plating	non noble metal	nickel	7440-02-0	0.076	0.02		213	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	214
solder	noble metal	silver	7440-22-4	0.086	0.02		240	
	non noble metal	tin	7440-31-5	0.069	0.02		192	
	non noble metal	lead	7439-92-1	3.272	0.92	0.96	9153	9585
*deviation	< 10%	Sum in total:			100,00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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